

# SPBT3.0DP2 module: some technical note about the Radio device embedded in the module, displayed in the Module Block Diagram as "STLC2690".

## 3 Bluetooth 3.1 Bluetooth functional description

## 3.1.1 Modem receiver

The Bluetooth subsystem implements a low-IF receiver for Bluetooth modulated input signals. The radio signal is taken from a balanced RF input and amplified by an LNA. The mixers are driven by two quadrature LO signals, which are locally generated from a VCO signal running at twice the frequency. The I and Q mixer output signals are band pass filtered by a poly-phase filter for channel filtering and image rejection. The band pass filter amplifies the signals to the optimal input range for the ADC. Further channel filtering is done in the digital part. The digital part demodulates the GFSK,  $\pi$ /4-DQPSK or 8-DPSK coded bit stream by evaluating the phase information. RSSI data is extracted. Overall automatic gain amplification in the receive path is controlled digitally. The RC time constants for the analog filters are automatically calibrated on chip.

## 3.1.2 Modem transmitter

The transmitter uses the serial transmit data from the Bluetooth controller. The transmitter modulator converts this data into GFSK,  $\pi/4$ -DQPSK or 8-DPSK modulated I and Q digital signals for respectively 1, 2 and 3 Mbps transmission speed. These signals are then converted to analog signals that are low pass filtered before up-conversion. The carrier frequency drift is limited by a closed loop PLL.

## 3.1.3 RF PLL

The on-chip VCO is part of a PLL. The tank resonator circuitry for the VCO is completely integrated without need of external components. Variations in the VCO center frequency are calibrated out automatically.

## 3.1.4 Bluetooth controller

## V1.2 and V2.0 + EDR Features

The Bluetooth controller is backward compatible with the Bluetooth specification V1.2 [4] and V2.0 + EDR [3]. Here below is a list with the main features of those specifications:

□ Adaptive Frequency Hopping (AFH)

□ Fast connection: interlaced scan for page and inquiry scan, answer FHS at first reception, RSSI used to limit range

□ Extended SCO (eSCO) links: supports EV3, EV4 and EV5 packets

□ Channel quality driven data rate change (CQDDR)

□ QoS flush

□ Synchronization: BT clocks are available at HCI level for synchronization of parallel applications on different Slaves

□ L2CAP flow & error control

□ LMP SCO handling

□ Scatternet support

- □ 2 Mbps packet types
- □ ACL: 2-DH1, 2-DH3, 2-DH5
- □ eSCO: 2-EV3, 2-EV5
- □ 3 Mbps packet types
- □ ACL: 3-DH1, 3-DH3, 3-DH5

- eSCO: 3-EV3, 3-EV5



## Bluetooth controller V2.1 + EDR features

- □ Encryption pause/resume (EPR)
- □ Extended inquiry response (EIR)
- □ Link supervision time out (LSTO)
- □ Secure simple pairing (SSP)
- □ Sniff subrating (SSR)
- □ Quality of service (QoS)
- □ Packet boundary flag (PBF)
- □ Erroneous data delivery (ED)

## **Bluetooth controller V3.0 features**

□ Enhanced power control

□ Read encryption key size

### TX output power control

The Bluetooth subsystem supports output power control:

□ With the standard TX power control algorithm enabled, the Bluetooth subsystem adapts its output power when a remote BT device supports the RSSI feature; this allows the remote device to measure the link strength and to request the Bluetooth subsystem to decrease/increase its output power. In case the remote device does not support the RSSI feature, the Bluetooth subsystem uses its 'default' output power level

The Bluetooth subsystem supports operation at Class 1 output power levels up to 10 dBm.

### 3.1.5 Main processor and memory

□ ARM7TDMI

□ On-chip RAM, including provision for patches

- □ On-chip ROM preloaded with
- □ SW up to HCI
- □ A2DP mediapacket encapsulation
- Patch RAM
- $\hfill\square$  The Bluetooth subsystem includes a HW block that allows patching of the ROM code.

□ Additionally, a SW patch mechanism allows replacing complete SW functions without changing the ROM image.

□ A part of the RAM memory is used for HW and SW patches.

## 3.1.6 CoProcessor

- □ Audio processor
- □ RAM, including provision for patches
- □ ROM, preloaded with
- □ SBC encoding/decoding
- Patch RAM
- □ a SW patch mechanism allows replacing complete SW functions without changing the ROM image.
- □ A part of the RAM memory is used for SW patches.

## Download of the SW parameter file

To change the device configuration a set of customizable parameters have been defined and put together in one file, the SW Parameter File. This SW Parameter File is downloaded at start-up into the Bluetooth subsystem.

Examples of parameters are: radio configuration, PCM settings etc.

The same HCI command is used to download the file containing the patches (both those for the SW and HW mechanism).

For a more detailed description of the SW Parameter File refer to [16].

#### 3.1.8 Pitch period error concealment (PPEC)

PPEC stands for pitch period error concealment. It is an algorithm and associated hardware used in the STLC2690 chip to improve the quality of voice transfer over the Bluetooth air channel. It provides for increased speech quality in the vicinity of interference, and improves the coexistence with WLAN. The



algorithm works at the receiver side and has no implications at all on the implementation of the Bluetooth specification.

PPEC works as follows: whenever a received packet is completely lost, instead of muting the output some previously received CVSD samples are inserted. These inserted samples are retrieved from a buffer. The PPEC algorithm continuously analyzes the samples that were previously received, and it uses fundamental speech properties to determine which samples from the buffer need to be inserted. As samples are just replaced, the PPEC algorithm does not add any latency to the voice transfer.

#### 3.1.9 Bluetooth – WLAN/WiMAX coexistence in collocated scenario

The coexistence interface uses up to 4 WLAN control signal pins, which can be mapped via the SW Parameter File download on different pins of the Bluetooth subsystem (see Section 4.1.7: "Download of the SW parameter file").

The functionality of the 4 WLAN control signal pins depends on the selected algorithm, as explained below and summarized in *Table 24: "WLAN HW signal assignment"*.

Bluetooth and WLAN 802.11 technologies occupy the same 2.4 GHz ISM band. The Bluetooth subsystem implements a set of mechanisms to avoid interference in a collocated scenario.

The Bluetooth subsystem supports 5 different algorithms in order to provide efficient and flexible simultaneous functionality between the two technologies in collocated scenarios:

□ **Algorithm 1:** PTA (packet traffic arbitration) based coexistence algorithm defined in accordance with the IEEE 802.15.2 recommended practice [7].

□ Algorithm 2: the WLAN is the Master and it indicates to the Bluetooth subsystem when not to operate in case of simultaneous use of the air interface.

□ Algorithm 3: the Bluetooth subsystem is the Master and it indicates to the WLAN chip when not to operate in case of simultaneous use of the air interface.

□ Algorithm 4: Two-wire mechanism

□ **Algorithm 5:** Alternating wireless medium access (AWMA), defined in accordance with the WLAN 802.11 technologies.

The algorithm is selected via an HCI command. The default algorithm is algorithm 1.

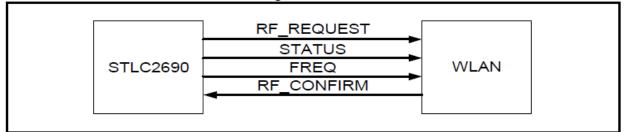
### Algorithm 1: PTA (packet traffic arbitration)

The algorithm is based on a bus connection between the Bluetooth subsystem and the WLAN chip

#### **Bluetooth STLC2690**

44/79 DocID022051 Rev 3 Figure 18: PTA

#### Figure 18: PTA



By using this coexistence interface it is possible to dynamically allocate bandwidth to the two devices when simultaneous operations are required while the full bandwidth can be allocated to one of them in case the other one does not require activity.

The algorithm involves

 $\Box$  a priority mechanism, which allows preserving the quality of certain types of link.

□ a mechanism to indicate that a periodic communication is ongoing.

A typical application would be to guarantee optimal quality to the Bluetooth voice communication while an intensive WLAN communication is ongoing.

Several algorithms have been implemented in order to provide a maximum of flexibility and efficiency for the priority handling. ST specific HCI commands are implemented to select the algorithm and to tune the priority handling.

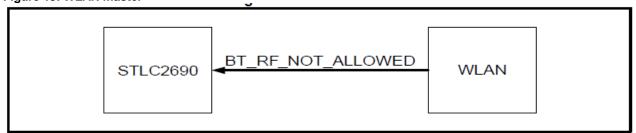
The combination of time division multiplexing and the priority mechanism avoids the interference due to packet collision. It also allows the maximization of the 2.4 GHz ISM bandwidth usage for both devices while preserving the quality of some critical types of link.



#### Algorithm 2: WLAN master

In case the Bluetooth subsystem has to cooperate, in a collocated scenario, with a WLAN chip not supporting a PTA based algorithm, it is possible to put in place a simpler mechanism. The interface is reduced to 1 line:

Figure 19: WLAN master



When the WLAN has to operate, it alerts high the BT\_RF\_NOT\_ALLOWED signal and the Bluetooth subsystem does not operate while this signal stays high.

This mechanism permits to avoid packet collision in order to make an efficient use of the bandwidth but cannot provide guaranteed quality over the Bluetooth links.

#### **Algorithm 3: Bluetooth Master**

This algorithm represents the symmetrical case of algorithm 2. Also in this case the interface is reduced to 1 line:

When the Bluetooth subsystem has to operate it alerts high the WLAN\_RF\_NOT\_ALLOWED signal and the WLAN does not operate while this signal stays high.

This mechanism permits to avoid packet collision in order to make an efficient use of the bandwidth, it provides high quality for all Bluetooth links but cannot provide guaranteed quality over the WLAN links.

#### Algorithm 4: Two-wire mechanism

Based on algorithm 2 and 3, the Host decides, on a case-by-case basis, whether WLAN or Bluetooth is Master. The Master role can be checked and changed at run-time by the Host via an HCI command.

Algorithm 5: Alternating wireless medium access (AWMA)

AWMA utilizes a portion of the WLAN beacon interval for Bluetooth operations. From a timing perspective, the medium assignment alternates between usage following WLAN procedures and usage following Bluetooth procedures.

The timing synchronization between the WLAN and the Bluetooth subsystem is done by the HW signal MEDIUM\_FREE.

#### WiMax co-existence interface

The WiMax co-existence interface connects a single wire between the STLC2690 and the WiMax controllers. The goal of the WiMax PTA implementation is to protect the traffic in the WiMax licensed bands adjacent to both ends of the 2.4 GHz ISM band used by Bluetooth. The WiMax disable pin is interpreted as a request to immediately shut down any ongoing or scheduled RF activity on the Bluetooth side. The WiMax system should assert this pin each time the Wimax RX activity takes place. The disable pin is directly connected to the BT radio control and BT shutdown can happen in less than 20 µs.

WLAN HW sig	gnal assignment				
Table 24: WLAN HW signal assignment WLAN control signal	Scenario 1: PTA	Scenario 2: WLAN Master	Scenario 3: BT Master	Scenario 4: 2- wire	Scenario 5: AWMA
WLAN 1	RF_CONFIRM	BT_RF_NOT_ALLO WED	Not used	BT_RF_NOT_ALLO WED	MEDIUM_FREE
WLAN 2	RF_REQUEST	Not used	WLAN_RF_NOT_A LLOWED	WLAN_RF_NOT_A LLOWED	Not used
WLAN 3 WLAN 4	STATUS FREQ (optional)	Not used Not used	Not used Not used	Not used Not used	Not used Not used



## 3.2 Bluetooth RF performance

All the values are provided according to the Bluetooth specification V3.0 unless otherwise specified.

### 3.2.1 Receiver

All specifications below are given at device pin level and with the conditions as specified. Parameters are given for each of the 3 modulation types supported.

(Typical is defined at  $T_{amb} = 25 \text{ °C}$ ,  $VDD_HV_x = 1.8 \text{ V}$ . Minimum and maximum are worst cases over corner lots and temperature. Parameters are given at device pin, except for receiver interferers measured at antenna with a filter having a typical attenuation of 2.3 dB, for filter details see [12]. Measured with an impedance of 26+j32 at the IC pins (this impedance is at 25 degrees, at low/high temp the impedance is changing with temperature).)

changing v						-		•• •
Table 25: 1	Parameter			Min.		Тур.	Max.	Unit
Mbps		con	dition					
receiver								
parameter								
s - GFSK								
Symbol								
RFin	•	freque	ncy 2	2402		2480		MHz
	range							
RXsensC	Receiver	-	BER	-92.5		-91	- 86.5	dBm
	sensitivity	0.19	%					
	(Clean							
	transmitter)							
RXsensD	Receiver		BER	-91.5		-90	-86	dBm
	sensitivity	0.19	%					
	(Dirty							
	transmitter	·						
	1))							
RXmax	Maximur		@ BER	R 0.1%	10		10	dBm
	useable							
	signal lev							
Receiver blo				R 0.1% o		nel 58 (wi		-
CW signal in			t signal		-7		dE	ßm
band 900 MH		strengtl	n = -67 d	IBm				
(824 MHz to	960							
MHz)		<u>.</u> .						
CW signal in			t signal	-	-3		dE	Sm
band 1800 M		strengtl	n = -67 d	IBm				
(1805 MHz to	0 1990							
MHz)								
CW signal in			t signal		-1		dE	sm
band		strengti	n = -67 d	IBM				
(2010 MHz to	2170							
MHz)	orforor porfe		~ @ PE	D 0 40/				
Receiver int	Co-chan							
C/Ico-channel					0 5		10	dD
			@ Inpu	It	8.5		10	dB
	interferer		signal		8.5		10	dB
			signal strengt		8.5		10	dB
C/Louis	interferer	nce	signal strengt dBm	h = -60			-	
C/I1MHz	interferer Adjacent	nce	signal strengt dBm @ Inpu	h = -60	8.5 -9		10 0	dB dB
C/I1MHz	interferer Adjacent MHz)	nce (±1	signal strengtl dBm @ Inpu signal	h = -60 t			-	
C/I1MHz	interferer Adjacent	nce (±1	signal strengtl dBm @ Inpu signal strengtl	h = -60 t			-	
	interferen Adjacent MHz) interferen	nce (±1 nce	signal strengtl dBm @ Inpu signal strengtl dBm	h = -60 it h = -60	-9		0	dB
C/I1MHz C/I+2MHz	interferen Adjacent MHz) interferen Adjacent	nce (±1 nce	signal strengt dBm @ Inpu signal strengt dBm @ Inpu	h = -60 it h = -60			-	
	interferen Adjacent MHz) interferen Adjacent MHz)	nce (±1 nce (+2	signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu signal	h = -60 it h = -60 it	-9		0	dB
	interferen Adjacent MHz) interferen Adjacent	nce (±1 nce (+2	signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu signal strengtl	h = -60 it h = -60 it	-9		0	dB
C/I+2MHz	interferen Adjacent MHz) interferen Adjacent MHz) interferen	nce (±1 nce (+2 nce	signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu signal strengtl dBm	h = -60 h = -60 h = -60	-9 -39		0 -30	dB dB
	interferen Adjacent MHz) interferen Adjacent MHz) interferen Adjacent	nce (±1 nce (+2 nce	signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu	h = -60 h = -60 h = -60	-9		0	dB
C/I+2MHz	interferen Adjacent MHz) interferen Adjacent MHz) interferen Adjacent MHz)	nce (±1 nce (+2 nce (-2	signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu	h = -60 it $h = -60$ it $h = -60$ it it	-9 -39		0 -30	dB dB
C/I+2MHz	interferen Adjacent MHz) interferen Adjacent MHz) interferen Adjacent	nce (±1 nce (+2 nce (-2	signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu signal strengtl	h = -60 it $h = -60$ it $h = -60$ it it	-9 -39		0 -30	dB dB
C/I+2MHz C/I-2MHz	interferen Adjacent MHz) interferen Adjacent MHz) interferen Adjacent MHz) interferen	nce (±1 nce (+2 nce (-2 nce	signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu signal strengtl dBm dBm	h = -60 h = -60 h = -60 h = -60 h = -67	-9 -39 -25		0 -30 -9	dB dB dB
C/I+2MHz	interferen Adjacent MHz) interferen Adjacent MHz) interferen Adjacent MHz) interferen	nce (±1 nce (+2 nce (-2 nce	signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu	h = -60 h = -60 h = -60 h = -60 h = -67	-9 -39		0 -30	dB dB
C/I+2MHz C/I-2MHz	interferen Adjacent MHz) interferen Adjacent MHz) interferen Adjacent MHz) interferen Adjacent MHz)	nce (±1 nce (+2 nce (-2 nce (+3	signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu	h = -60 h = -60 h = -60 h = -67 h = -67	-9 -39 -25		0 -30 -9	dB dB dB
C/I+2MHz C/I-2MHz	interferen Adjacent MHz) interferen Adjacent MHz) interferen Adjacent MHz) interferen	nce (±1 nce (+2 nce (-2 nce (+3	signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu	h = -60 h = -60 h = -60 h = -67 h = -67	-9 -39 -25		0 -30 -9	dB dB dB
C/I+2MHz C/I-2MHz	interferen Adjacent MHz) interferen Adjacent MHz) interferen Adjacent MHz) interferen Adjacent MHz)	nce (±1 nce (+2 nce (-2 nce (+3 nce	signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu signal strengtl dBm @ Inpu	h = -60 h = -60 h = -60 h = -67 h = -67 h = -67	-9 -39 -25		0 -30 -9	dB dB dB



C/I≥4MHz	MHz) interference Adjacent (≥ ±4 MHz) interference	signal strength = -67 dBm @ Input signal strength = -67 dBm	-45		-40	dB
Symbol F	1 Rev 3 47/79 Parameter Te	est Min. Indition		Тур.	Max.	Unit
Receiver inter-	modulation					
IMD	Inter- modulation	Measured as defined in BT test specification [6]	-39		-32.3	dBm

#### Notes:

(1) Dirty transmitter including carrier frequency drift, as defined in the BT SIG spec [6].

(Typical is defined at  $T_{amb} = 25$  °C, VDD\_HV\_x = 1.8 V. Minimum and maximum are worst cases over corner lots and temperature. Parameters are given at device pin, except for receiver interferers measured at antenna with a filter having a typical attenuation of 2.3 dB, for filter details see [12]. Measured with an impedance of 26+j32 at the IC pins (this impedance is at 25 degrees, at low/high temp the impedance changes with temperature).

Table 27: 3 Mbps receiver parameters - 8-DPSK Symbol	Parameter	Test condition	Min.	Тур.	Max.	Unit
RFin	Input fr range	equency	2402	2480	Ν	1Hz
RXsensC	Receiver sensitivity (Clean transmitter)	@ BER 0.01%	-85	-83	-78.5	dBm
RXsensD	Receiver sensitivity (Dirty transmitter(1))	@ BER 0.01%	-84	-82	-77.5	dBm
RXmax	Maxim	um useable gnal level	@ BER 0.1%	-3	d	Bm
Receiver block		0	% on channel 5	8 (without filter)		
CW signal in G 900 MHz (824 MHz to 96	SM band (	Input signal trength = -67 d	-11	•	dBm	
CW signal in G 1800 MHz (1805 MHz to 1	SM band (	Input signal trength = -67 d	-7 Bm		dBm	
CW signal in W band (2010 MHz to 2	CDMA (@s	Input signal trength = -67 d	-9 Bm		dBm	

#### Receiver interferer performance @ BER 0.1%



C/Ico-channel	Co-channel interference	@ Input signal strength = -60 dBm	19	21	dB
C/I1MHz	Adjacent (±1 MHz) interference	@ Input signal strength = -60 dBm	-5	5	dB
C/I+2MHz	Adjacent (+2 MHz) interference	@ Input signal strength = -60 dBm	-37	-25	dB
С/І-2МНz	Adjacent (-2 MHz) interference	@ Input signal strength = -67 dBm	-12	0	dB
C/I+змнz	Adjacent (+3 MHz) interference	@ Input signal strength = -67 dBm	-46	-33	dB
С/І-змнz	Adjacent (-3 MHz) interference	<ul> <li>Input signal</li> <li>strength = -67</li> <li>dBm</li> </ul>	-40	-13	dB
C/I≥4MHz	Adjacent (≥ ±4 MHz) interference	@ Input signal strength = -67 dBm	-42	-33	dB

#### Notes:

(1) Dirty transmitter including carrier frequency drift, as defined in the BT SIG spec [6].

## 3.2.2 Transmitter



(Unless otherwise stated, typical is defined at  $T_{amb} = 25 \text{ °C}$ ,  $VDD_HV_x = 1.8 \text{ V}$ . Minimum and maximum are worst cases over corner lots and temperature. Parameters are given at device pin, except for in-band spurious measured at antenna with a filter having a typical attenuation of 2.3 dB, for filter details see [12]. Measured with an impedance of 26+j32 at the IC pins (this impedance is at 25 degrees, at low/high temp the impedance changes with temperature).)

Table 28:	Parameter	Test	Min.	Тур.	Max.	Unit
Transmitter Parameters		condition				
Symbol						
RFout	Output fi range	requency	2400	2483.	5	MHz
RF transmit po						
TXpout	Maximum	@ 2402 -	8	10	12	dBm
(GFSK)	output	2480 MHz				
	power(1)	@ 25 °C				
TXpout	Maximum	@ 2402 -	7	10	13	dBm
(GFSK)	output	2480 MHz				
	power(1)	@ worst				
		cases over				
		corner lots				
		and				
<b>T</b> 1/		temperature				10
TXprange	Power c	ontrol range	@ 2402 - 248	80 MHz 40		dB
(GFSK, π/4- DQPSK, 8- DPS	SK)					
Resolution of po		0.25			dB	
TXpout	Maximum	@ 2402 -	5	7	9	dBm
(π/4-	output	2480 MHz	0	I	0	abiii
DQPSK)	power(1) (3)	@ 25 °C				
TXpoutrel	Relative	@ 2402 -	0	-0.5	-1	dB
(π/4-	transmit	2480 MHz	-		-	
DQPSK)	power(4)					
TXpout	Maximum	@ 2402 -	5	7	9	dBm
(8-DPSK)	output	2480 MHz				
	power(1) (2)	@ 25 °C				
TXpoutrel	Relative	@ 2402 -	0	-0.5	-1	dB
(8-DPSK)	transmit	2480 MHz				
In hand an use	power(3)					
FCC	us emissions(5) FCC's 2		935	970		kHz
ACP_2		offset = $\pm 2$	-39	-20		dBm
A01_2	MHz	01361 - ±2	-39	-20		ubiii
ACP_3		offset = $\pm$ -3	-47	-40		dBm
	MHz					42
ACP_4	Channel	offset ≥ ±4	-50	-40		dBm
	MHz					
EDR_IBS_1		offset = $\pm 1$	-27	-26		dBc
		and 3 Mbps)				
EDR_IBS_2		offset = $\pm 2$	-28	-20		dBm
	MHz (2 a	and 3 Mbps)				
Symbol	Parameter	Test	Min.	Тур.	Max.	Unit
		condition				
EDR_IBS_3		el offset = $\pm 3$	-44	-40		dBm
		and 3 Mbps)	47	40		dD as
EDR_IBS_4		el offset = $\pm 4$	-47	-40		dBm
Initial carrier fr	equency tolera	and 3 Mbps)	act reference	N		
	f_TX-f0	-75		<b>0</b> (6)	75	kHz
Carrier frequer		10		0(0)	10	KI IZ
∆f_s		frequency	3.2	10		kHz
· -··	stability					
Carrier frequer	ncy drift <sub>(8)</sub>					
∆f_p1		t packet	12 <i>(</i> 5)	25		kHz
∆f_p3		lots packet	14 <i>(</i> 5)	40		kHz
∆f_p5	Five slo	ts packet	14 <i>(</i> 5)	40		kHz



Carrier frequency d	rift rate(7)						
Δf/50us	Frequency drift rate	8		20			kHz/50µs
Modulation accurac							
	Maximum 140		163		175		kHz
r	nodulation						
∆f2avg	Minimum modulation	115		140			kHz
Δf2avg/ Δf1avg	0.8				0.9		
2-DH5 RMS DEVM	7.2		20			%	
2-DH5 99% DEVM	30				%		
2-DH5 Peak DEVM	17.5		35			%	
3-DH5 RMS DEVM	7.2		13			%	
3-DH5 99% DEVM	20				%		
3-DH5 Peak DEVM	15		25			%	
TX out of band emis	sions						
E100	Emission in FM band	(7) (10)		-123			dBm/Hz
	(76-108 MHz)						
E700	Emission in	(7) (9)		-135			dBm/Hz
	CDMA2000 band						
	(776-794 MHz)						
E850	Emission in GSM	(7) (9)		-134			dBm/Hz
	band						
	(869-960 MHz)						
E900	Emission in GSM	(7) (9)		-134			dBm/Hz
	band						
	(925-960 MHz)	(7) (0)					
E1500	Emission in GPS	(7) (9)		-140			dBm/Hz
	band						
<b>E</b> 4000	(1570-1580 MHz)	(7) (9)		400			ID // I
E1800	Emission in GSM	(7) (3)		-136			dBm/Hz
	band						
F1000	(1805-1880 MHz)	(7) (9)		400			alDuce /L Im
E1900	Emission in GSM	(7)(0)		-136			dBm/Hz
	band						
	(1930-1990 MHz)						

Symbol	Parameter	Test condition	Min.	Тур.	Max.	Unit
E2100		n in WCDMA 110- 2170	(7) (9)	-136		dBm/Hz
E2600	band	n in WCDMA 690 MHz)	(7) (9)	-135		dBm/Hz
E5000	band	n in WLAN 825 MHz)	(7) (9)	-130		dBm/Hz

Notes:

(1) Lower transmit power (i.e. Class 2) can be obtained by programming the radio init power table via the SW Parameter File download or an HCI command.

(2) The step size can be controlled via the SW Parameter File.

(3) Power of GFSK part.

(4) Relative power of EDR part compared to the GFSK part.

(5) At antenna with maximum output power, filter attenuation of 2.3 dB.

(6) Phase noise adds maximum [-10 kHz;10 kHz] for worst case clock 200 mVpp at 13 MHz.
 (7) Worst case clock 200 mVpp at 13 MHz. Measurement according to EDR RF test spec V2.0.E.3

(8) With maximum output power.

(9) Measured on reference schematic following layout recommendations.

(10) Transmitting DH5 packets.

## 3.3 Bluetooth interfaces



## 3.3.1 HCI transport layer

### H4 UART transport layer

The HCI transport layer supported on the UART is the H4 transport layer defined by the SIG [5]. The HCI UART transport layer assumes that the UART communication is free from line errors.

The UART interface is defined in Section 3.12.2: "UART interface".

Two ways to enter and exit the low power modes are supported (For more details, refer to [15]):

□ H4 UART: using CLK\_REQ\_OUT\_x, UART\_RXD and UART\_RTS.

□ H4 UART with handshake: using CLK\_REQ\_OUT\_1, BT\_WAKEUP and HOST\_WAKEUP.

## Enhanced H4 SPI transport layer

The HCI transport layer supported on the SPI is the H4 transport layer defined by the SIG [5]. The HCI SPI transport layer assumes that the SPI communication is free from line errors.

In addition a messaging protocol is defined for controlling the Deep Sleep mode entry and wake-up. Three messages are defined: SLEEP, WAKEUP and WOKEN. For more details, refer to [14].

The SPI interface is defined in Section 3.12.4: "FM I2C interface".

One way to enter and exit the low power modes is supported (for more details, refer to

• Enhanced H4 SPI: using CLK\_REQ\_OUT\_x and the SPI in band signaling.

#### (e)SCO over HCI

The STLC2690 supports synchronous data packet transfer ((e)SCO) over HCI.

### 3.3.2 BT audio interface

The Bluetooth subsystem of STLC2690 supports one audio interface which can be used for (e)SCO voice transmission and reception or for A2DP. This interface can be either the BT PCM or the BT I2S as defined in *Sections 2.12.5* and *2.12.8* 

The interface is fully configurable by the Host via the SW Parameter File download and when a SCO connection or A2DP connection is started-up (in order to allow different configuration based on use case). It is possible to configure 2 SCO connections on the PCM interface taking advantage of the multi-port PCM support. The configuration of the PCM for the second SCO is not disturbing the first SCO connection. For Bluetooth voice operation (PCM/I2S and (e)SCO), the interface always works at 8 kHz. However, it is possible to configure the interface to other frame rates like 16 or 32 kHz, and link it to an eSCO link operating at the same rate. In I2S mode, it is possible to exchange voice on the left or on the right channel only. When two (e)SCO are active, each SCO uses one of the channels. The channel which is not used is padded with '0' on data out.

For A2DP operation, the I2S sample rate is configurable e.g. 44.1 or 48 kHz. The audio is SBC encoded and A2DP encapsulated in the STLC2690, before being transmitted over the BT link.

#### 3.3.3 WLAN/WiMAX coexistence interface

The WLAN/WiMAX coexistence interface to a WLAN and/or WiMAX chip allows optimal coexistence between the two functions when collocated. This interface can contain 1 to 4 wires (WLAN1, WLAN2, WLAN3 and WLAN4). For more details refer to Section 4.1.9: "Bluetooth – WLAN/WiMAX coexistence in collocated scenario". The 4 control signals are mapped on the pins as indicated in Section 3.4.3: "Pin mapping".

## 3.3.4 **GPIOs**

Up to 22 GPIOs can be mapped to the pins. These GPIOs can be used as a generic output or input (interrupt) signals.



# SPBT3.0DP2 module: some technical note about the Antenna device embedded in the module, displayed in the Module Block Diagram as "internal RF antenna".

# ANTENNA DESCRIPTION

The supplier of the module internal antenna is:

JOHANSON TECHNOLOGY

www.johansontechnology.com 001 Calle Tecate • Camarillo, CA 93012 • TEL 805.389.1166 FAX 805.389.1821 /er 1.3 2014 Johanson Technology, Inc. All Rights Reserved

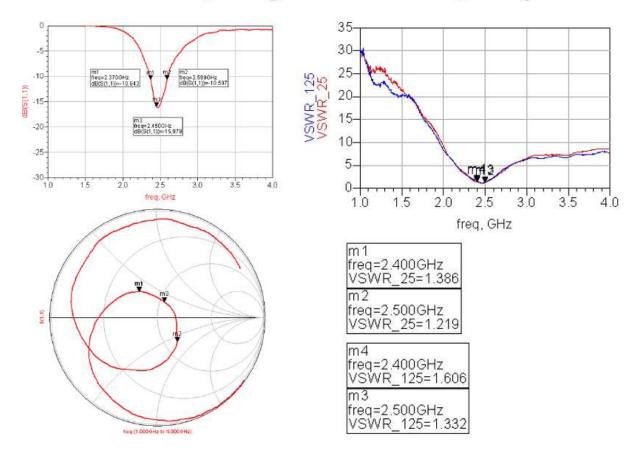
General Specifications	
Part Number	2450AT18A100
Frequency Range	2400 - 2500 Mhz
Peak Gain	0.5 dBi typ. (XZ-V)
Average Gain	-0.5 dBi typ. (XZ-V)
Return Loss	9.5 dB min.
Input Power	2W max. (CW)
Impedance	50 Ω
Operating Temperature	-40 to +125°C
Reel Quanity	3,000



Me	Mechanical Dimensions					
	In	mm				
L	0.126 ± 0.008	3.20 ± 0.20	w → ← <sup>a</sup>			
W	0.063 ± 0.008	1.60 ± 0.20				
Т	0.051 +.004/008	1.30 +0.1/-0.2				
а	0.020 ± 0.012	0.50 ± 0.30	L			



## Antenna electrical characteristic



## Return Loss with matching circuit @ +25C VSWR with matching circuit @ +25C and +125C